# PCA9522

## Fast dual bidirectional bus buffer with hot insertion logic

Rev. 1 — 28 September 2011 Product data sheet

## 1. General description

The PCA9522 is a monolithic bipolar integrated circuit for bus buffering in applications including I$^2$C-bus, SMBus, etc. It includes hot insertion logic for detecting stop and idle conditions, making it ideal for live insertion into backplanes. The buffer extends the bus load limit by buffering both the SCL and SDA lines. The PCA9522 is a drop-in replacement for the IES5502, with only the maximum bus voltage reduced from 15 V to 10 V.

Hot insertion logic allows the IC to be plugged into live backplanes without causing data corruption on the bus. The open-collector ready signal (RDY) indicates when the connection has been made. Precharging of the backplane ports minimizes disruptions to the bus during hot insertion.

The enable function allows sections of the bus to be isolated. Individual parts of the system can be brought on-line successively. Bus level translation between a very wide range of bus voltages, from 1.8 V to 10 V, is supported. These features provide enormous flexibility in interfacing systems of different technologies, operating speeds and loads.

The unique operation of the PCA9522 provides one of the fastest response times of such bidirectional buffers. It does this without the need for rise-time accelerators which, combined with low noise margins, may cause glitches outside of the I$^2$C-bus specification.

## 2. Features and benefits

- Dual, bidirectional unity gain isolating buffer
- Hot insertion logic prevents data and clock bus corruption for live backplane applications
- Pre-charge minimizes data corruption on live insertion
- Supports I$^2$C-bus (Standard-mode and Fast-mode), SMBus (standard and high power modes) and PMBus
- Open-collector ready output (RDY)
- Fast switching times allow operation in excess of 1 MHz
- Enable (EN) allows bus segments to be disconnected
- Low current standby mode when not enabled
- High-impedance ports when IC unpowered
- 6 mA (static) pull-down capability
- Low noise susceptibility
- Supports the connection of several buffers in series
- Level shift bus voltages from 1.8 V to 10 V

## 3. Applications

- Backplane management/interconnect
- Telecommunications systems including ATCA
- Desktop and portable computers including RAID

## 4. Ordering information

**Table 1. Ordering information**

| Type number | Topside mark | Package | | |
|---|---|---|---|---|
| | | Name | Description | Version |
| PCA9522D | PCA9522 | SO8 | plastic small outline package; 8 leads; body width 3.9 mm | SOT96-1 |
| PCA9522DP | 9522 | TSSOP8 | plastic thin shrink small outline package; 8 leads; body width 3 mm | SOT505-1 |

## 5. Block diagram

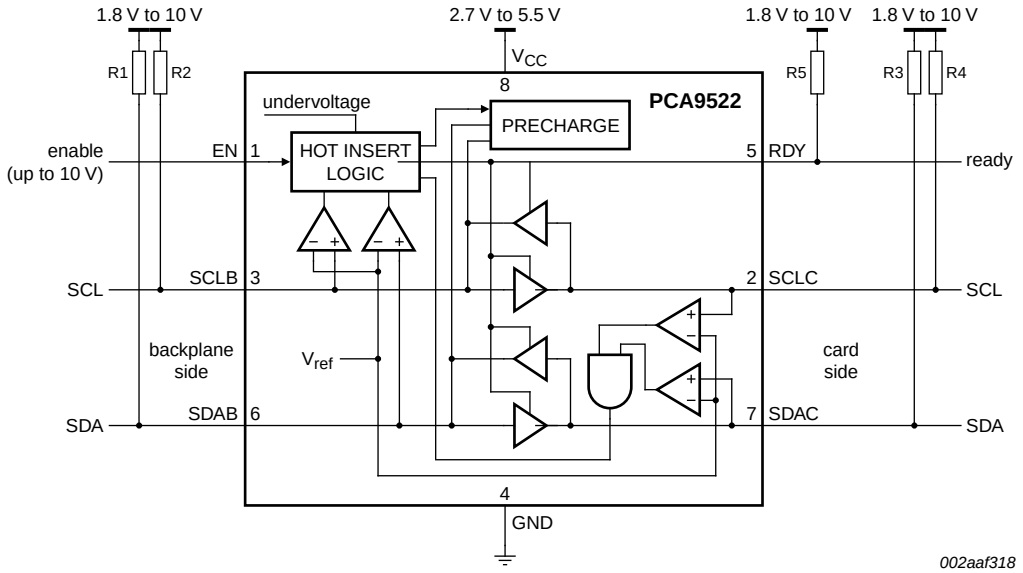



**Fig 1. Block diagram of PCA9522**


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# 6. Pinning information

## 6.1 Pinning

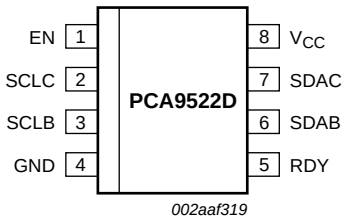



Fig 2. Pin configuration for SO8

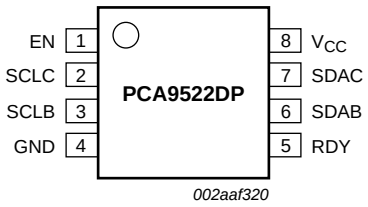



Fig 3. Pin configuration for TSSOP8

## 6.2 Pin description

Table 2. Pin description

| Symbol | Pin | Description |
|---|---|---|
| EN | 1 | enable |
| SCLC | 2 | SCL buffer, card side[1] |
| SCLB | 3 | SCL buffer, backplane side[2] |
| GND | 4 | supply ground |
| RDY | 5 | ready |
| SDAB | 6 | SDA buffer, backplane side[2] |
| SDAC | 7 | SDA buffer, card side[1] |
| $V_{CC}$ | 8 | positive supply |

[1] Card side is equivalent to SCL_OUT / SDA_OUT.

[2] Backplane side is equivalent to SCL_IN / SDA_IN.


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# 7. Functional description

Refer to Figure 1 “Block diagram of PCA9522”.

## 7.1 $V_{CC}$, GND — supply pins

The PCA9522 can be driven from voltage supplies ranging from 2.7 V to 5.5 V. The threshold level below which the output will begin to match the input is 33 % of $V_{CC}$. Hence, the operating voltage should be chosen with the required bus voltage, switching threshold, and noise margins in mind.

## 7.2 SCLB, SCLC, SDAB, SDAC — buffer inputs/outputs

The two open-collector buffers (SCL and SDA) are identical and symmetrical. The buffers can be driven from either direction, with the same buffering response. However, the hot insertion logic is determined from the ‘backplane’ (SxxB) sides of the buffers. When the one side (e.g., SxxB) of the buffer is being driven LOW (<0.3$V_{CC}$) by another device on the bus, the other side (e.g., SxxC) will be driven LOW by the IC to provide the buffered output.

The ‘control’ or ‘input’ side is determined by the lowest externally driven signal. Therefore if the ‘input’ is externally pulled to $V_{SxxB}$ = 250 mV, and the ‘output’ is externally pulled to $V_{SxxC}$ = 500 mV, the buffer will pull the ‘output’ down further such that it becomes $V_{SxxC} = V_{SxxB} + V_{offset}$. Should the ‘output’ subsequently become lower than the ‘input’ by means of an external device pulling it LOW ($V_{SxxC} < V_{SxxB}$), control of the buffering operation will switch sides. The voltage at the ‘input’ will then become $V_{SxxB} = V_{SxxC} + V_{offset}$. Many bus buffers are prone to causing glitches during control transition, but the PCA9522 shows negligible glitching even under the worst operating conditions.

## 7.3 Enable (EN) — activate buffer operations

The enable input (EN) is used to disable the buffer, for the purpose of isolating sections of the bus. The IC should only be disabled when the bus is idle, to prevent truncation of commands which may confuse other devices on the bus.

Upon receiving a valid enable (EN) signal, the IC will wait to detect either a bus STOP condition, or an IDLE condition as described in the $I^2C$-bus [Ref. 1] and SMBus [Ref. 2] specifications. This ensures that truncated transmissions are not communicated along the newly enabled bus segment.

Enable may be used to progressively activate sections of the bus during system start-up. Bus sections slow to respond on power-up can be kept isolated from the main system to avoid interference and collisions.

The EN pin may be pulled up higher than the $V_{CC}$ of the buffer, further enhancing the capability of the PCA9522 in a level shifting role. For example, a microprocessor could drive EN, SCLB and SDAB at 5 V, while the buffer $V_{CC}$, SCLC and SDAC ports are at 3.3 V.

Similarly, the threshold level of the EN pin allows a 1.8 V device to enable an PCA9522 with a $V_{CC}$ of 3.3 V.


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### 7.4 Ready (RDY) — buffer connected indicator

The ready output (RDY) indicates that the buffer has met its enable conditions, and that communication will now occur. This is an open-collector transistor which is switched off when ready, allowing the voltage at the pin to be pulled HIGH by a pull-up resistor.

### 7.5 Start-up

During power-up or live insertion into backplanes, the PCA9522 will start-up in an UnderVoltage LockOut (UVLO) state where any activity on the input/output ports will be ignored. This is to ensure that the PCA9522 does not try to operate when there is not enough voltage on the supply.

During this time, the precharge circuit will charge all SCLB/SDAB backplane ports to typically 0.92 V. This will minimize any voltage difference between the ports and hence minimizes disruptions to the bus during hot insertion into backplanes.

When the supply increases above the UVLO state the PCA9522 will then monitor the bus for either stop bit or bus idle condition. When a stop bit condition is detected and SCLC/SDAC are both idle or when all SCL/SDA ports idle for a time period of typically 95 μs, then the PCA9522 will activate the input-output connection circuitry. The precharge circuitry is switched off. The voltage at the RDY pin is pulled HIGH by an external pull-up resistor to indicate the input/output connection has been made.

## 8. Limiting values

**Table 3. Limiting values**

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|---|---|---|---|---|---|---|
| $V_{CC}$ | supply voltage | | [1] | −0.3 | +7 | V |
| $V_n$ | voltage on any other pin | SCLB, SCLC, SDAB, SDAC | [1] | −0.3 | +12 | V |
| $V_{I(EN)}$ | input voltage on pin EN | | [1] | −0.3 | +12 | V |
| $I_{IO}$ | input/output current | DC; any pin | | - | 20 | mA |
| $P_{tot}$ | total power dissipation | | | - | 300 | mW |
| $T_{stg}$ | storage temperature | | | −55 | +125 | °C |
| $T_{amb}$ | ambient temperature | operating | | −40 | +85 | °C |

[1] Voltages are specified with respect to pin 4 (GND).


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# 9. Characteristics

**Table 4. Characteristics**

*$T_{amb}$ = −40 °C to +85 °C; voltages are specified with respect to ground (GND).*

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| **Power supply** | | | | | | |
| $V_{CC}$ | supply voltage | operating | 2.7 | - | 5.5 | V |
| $I_{CC}$ | supply current | operating; $V_{CC}$ = $V_{I(EN)}$ = 5.5 V | - | 9 | - | mA |
| | | standby; $V_{CC}$ = 5.5 V; $V_{I(EN)}$ = 0 V | - | 520 | - | µA |
| **Start-up circuitry** | | | | | | |
| $V_{th(UVLO)}$ | undervoltage lockout threshold voltage | $V_{CC}$ = $V_{I(EN)}$ = 5.5 V | - | 2.2 | - | V |
| $V_{pch}$ | precharge voltage | $V_{SxxB}$ floating; $V_{CC}$ = 3.3 V; $V_{i(EN)}$ > 1.2 V | - | 0.92 | - | V |
| $I_{pch}$ | precharge current | $V_{SxxB}$ floating; $V_{CC}$ = 3.3 V; $V_{i(EN)}$ > 1.2 V | - | 11 | - | µA |
| $V_{th}$ | threshold voltage | logic input | - | $0.5V_{CC}$ | - | V |
| | | logic output | - | $0.5V_{CC}$ | - | V |
| **Buffer ports (SCLB, SCLC, SDAB, SDAC)** | | | | | | |
| $V_{bus}$ | bus voltage | | - | - | 10 | V |
| $V_{th(IL)}$ | LOW-level input threshold voltage | | - | - | $0.3V_{CC}$ | V |
| $V_{th(IH)}$ | HIGH-level input threshold voltage | | $0.41V_{CC}$ | - | - | V |
| $I_{IL}$ | LOW-level input current | drive current; $V_{bus}$ < $V_{CC}$ | - | −10 | −20 | µA |
| $I_{O(sink)}$ | output sink current | LOW-level; $V_{bus(out)}$ = 0.4 V | 6 | - | - | mA |
| $V_{offset}$ | offset voltage | input/output; $V_{CC}$ = 3.3 V | | | | |
| | | $I_{OL}$ = 4 mA; $V_{bus(in)}$ = 50 mV | - | 165 | 200 | mV |
| | | $I_{OL}$ = 500 µA; $V_{bus(in)}$ = 50 mV | - | 55 | 100 | mV |
| | | $I_{OL}$ = 1.2 mA; $V_{bus(in)}$ = 200 mV | - | 60 | 100 | mV |
| $I_L$ | leakage current | $V_{bus}$ = $V_{CC}$ | - | - | 5 | µA |
| **Enable (EN)** | | | | | | |
| $V_{en}$ | enable voltage | active | 1.2 | - | - | V |
| $V_{dis}$ | disable voltage | standby | - | - | 0.7 | V |
| $I_I$ | input current | $V_{en}$ > 1.2 V | 1 | - | 5 | µA |
| **Ready (RDY)** | | | | | | |
| $V_{OL(RDY)}$ | LOW-level output voltage on pin RDY | $I_{pu}$ = 3 mA | - | - | 400 | mV |
| $I_L$ | leakage current | $V_{OL(RDY)}$ = $V_{CC}$ | - | - | ±5 | µA |
| **Timing characteristics**[1] | | | | | | |
| $t_d$ | delay time | $V_{CC}$ = 5 V; $V_{bus}$ = 5 V; $R_{pu(bus)}$ = 1 kΩ; $C_{L(ext)}$ = 120 pF; Figure 4 | - | 30 | - | ns |
| $t_f$ | fall time | $V_{CC}$ = 5 V; $V_{bus}$ = 5 V; $R_{pu(bus)}$ = 1 kΩ; $C_{L(ext)}$ = 120 pF; Figure 4 | - | 15 | - | ns |
| $f_{oper}$ | operating frequency | | 0 | 400 | - | kHz |


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**Table 4. Characteristics** *...continued*

*$T_{amb}$ = −40 °C to +85 °C; voltages are specified with respect to ground (GND).*

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|---|---|---|---|---|---|---|
| $t_{idle}$ | idle time | $V_{bus} = V_{I(EN)} = V_{CC}$ = 3.3 V | 50 | 95 | 150 | µs |
| | | $V_{bus} = V_{I(EN)} = V_{CC}$ = 5.5 V | 50 | 75 | 120 | µs |
| $t_{d(ENH-RDYoff)}$ | delay time from EN HIGH to RDY off | | - | 95 | - | µs |
| $t_{d(ENL-RDYon)}$ | delay time from EN LOW to RDY on | | - | 1.1 | - | µs |
| $t_{d(RDYH-I2Con)}$ | delay time from RDY HIGH to $I^2C$ on | | - | 1 | - | µs |
| $t_{d(RDYL-I2Coff)}$ | delay time from RDY LOW to $I^2C$ off | | - | −0.5 | - | µs |

[1] Guaranteed by design (not subject to test), except for $t_{idle}$ at $V_{CC}$ = 3.3 V.

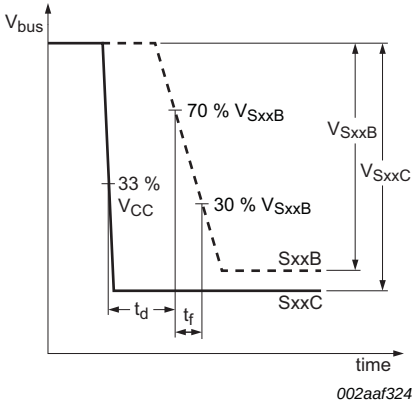
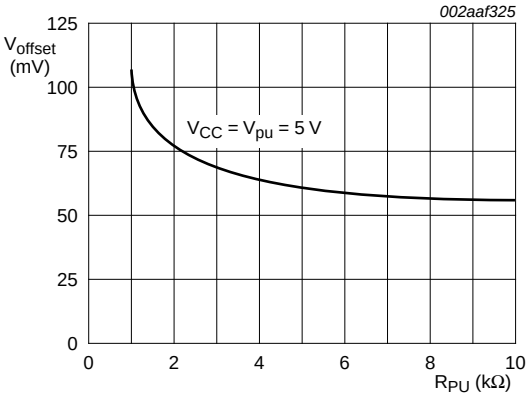



**Fig 4. Timing parameters**




$T_{amb}$ = 25 °C; $V_{bus(in)}$ = 200 mV.

**Fig 5. Offset voltage, $V_O - V_I$**

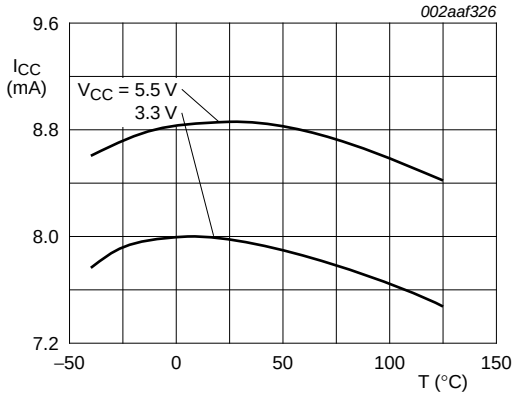



**Fig 6. Supply current versus temperature**


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# 10. Application information

## 10.1 Design considerations

Figure 7 shows a typical application for the PCA9522. The IC can level shift between various bus voltages, without the need for additional external components. Higher bus voltages and currents outside the range of the standard $I^2C$-bus specification can be catered for, providing a longer range capability and higher noise immunity.

The enable pin (EN) can be used to interface buses of different operating frequencies. When enabled, the bus frequency is limited to the maximum 100 kHz of the slave device. When disabled, the slave is isolated, and the remaining bus can be run at 400 kHz. The timing performance and current sinking capability will allow it to run well in excess of the 400 kHz maximum limit of the Fast-mode $I^2C$-bus.

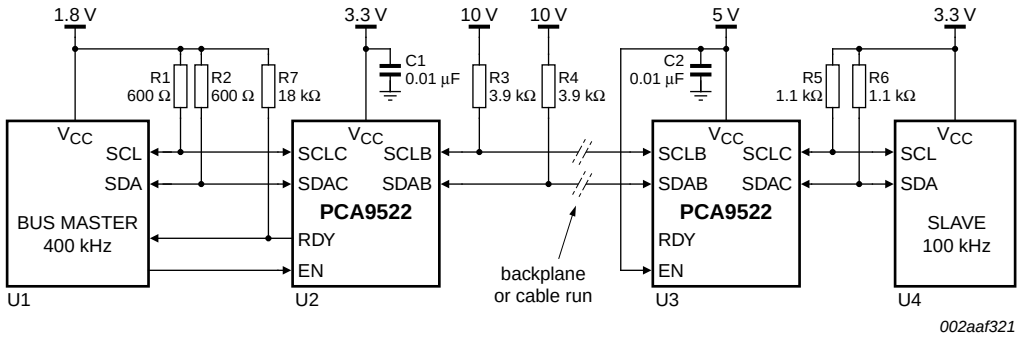



**Fig 7. PCA9522 typical buffer application**

Figure 8 shows the PCA9522 used in a backplane application. Peripheral cards and backplanes operating at a range of voltages can be interfaced together using a minimum of components. In this example, cards are running at 1.8 V and 3.3 V, while the backplane is at 5 V. Cards operating buses between 1.8 V and 10 V can be catered for in the same system.

Each card can be safely isolated from the system by disabling the PCA9522 at the interface to the backplane. The hot insertion logic on the PCA9522 protects against corrupted or truncated data transmissions on start-up of buffer operations.


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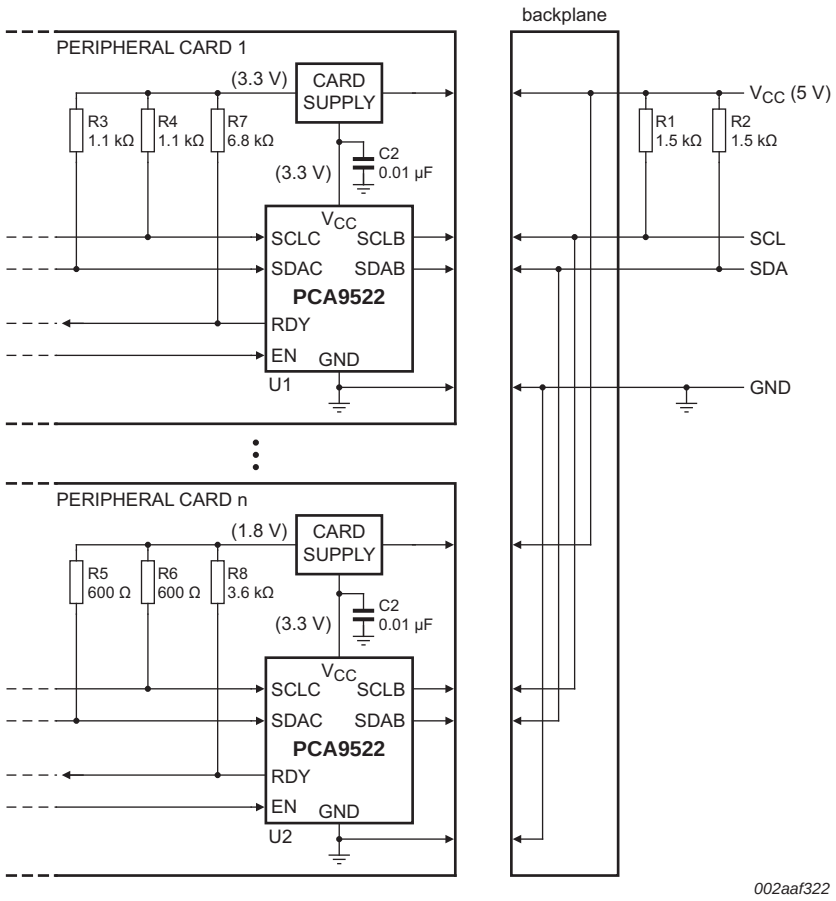


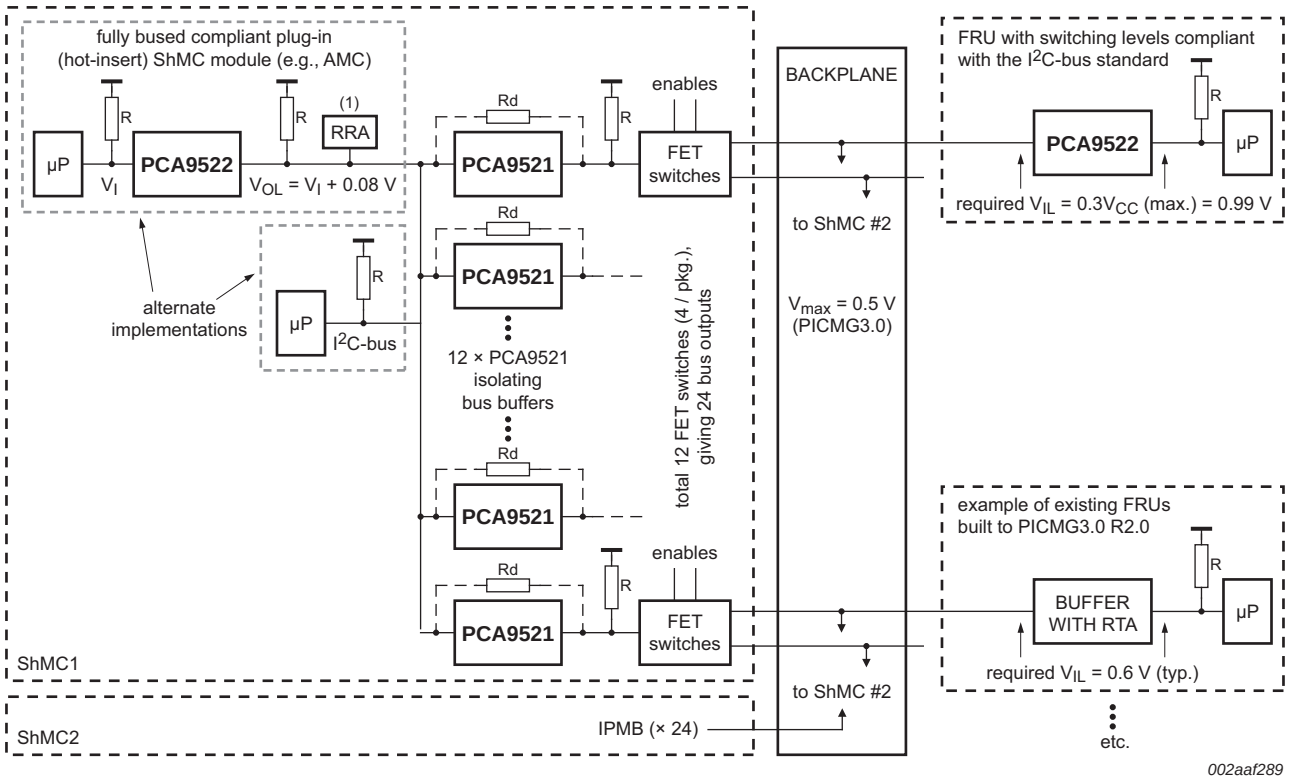

**Fig 8. PCA9522 backplane application**

An ideal backplane application for the PCA9522 is the Advanced Telecom Computing Architecture (AdvancedTCA) as shown in Figure 9. The PCA9522 is well-suited to placement on 'Field Replaceable Units' (FRUs) used in either a conventional fully-bused arrangement (not shown) or in the low cost, high noise margin radial architecture example as shown in Figure 10. It is fully interoperable with existing systems and components. If required, Figure 10 shows a simple low-cost circuit for use at the Shelf Manager for accelerating the rise in bused systems.

In each of these examples, the buffers are intended to extend total system capacitance above 400 pF, so anticipate high capacitance on each side. When loading on one side is small, adding 47 pF is suggested to avoid any waveform ripple, should it occur.


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The system shown here uses FET switches, however a valid alternative is to simply use 24 × PCA9521s without FET switches.

Long track runs on the ShMC board and backplane can sometimes result in high frequency tuned circuits on either side of the PCA9521. If your layout is prone to forming such tuned circuits, it is perfectly acceptable to use a 'traditional' damping resistor (Rd) across the PCA9521.

(1) RRA = Rise Rate Accelerator.

**Fig 9. PCA9522 used in an AdvancedTCA application in conjunction with the PCA9521**

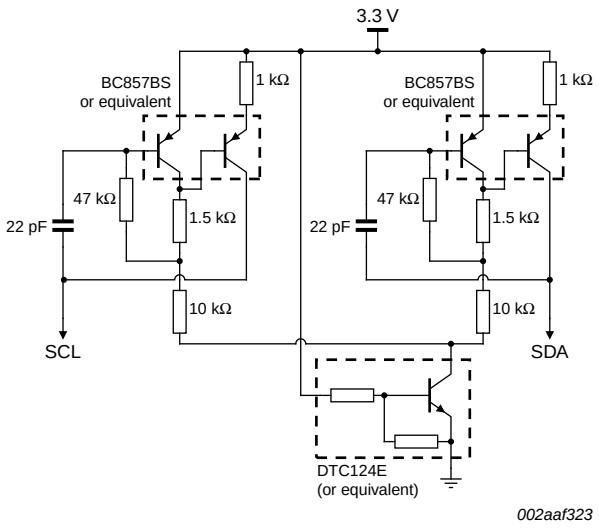



**Fig 10. Discrete rise rate accelerator circuit example**


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## 10.2 Input to output offset voltage calculation

The offset voltage between the side acting as the output (Sxxx(out)) and the side acting as the input (Sxxx(in)) of the PCA9522 can be calculated using the relationship given in Equation 1:

$$V_{offset} = V_i + 50\ mV + \left(\frac{V_{BUS}}{R}\right) \times 11 \quad (1)$$

This calculation is valid for $V_{Sxxx(in)} \geq 200$ mV, as below this point the saturation voltage of the open-collector output drive transistor will begin to affect the characteristic. Input and output voltages are shown in millivolts, $V_{BUS}$ (the supply voltage to the bus) is in volts, and R is in ohms.

An example calculation for $V_{BUS}$ = 3.3 V, $V_{SxxC}$ = 200 mV, the resistance R pulling up SxxB is 2 kΩ, then the voltage on SxxB is typically:

$$V_{SxxB} = 200\ mV + 50\ mV + \left(\frac{3.3}{2000}\right) \times 11 = 268\ mV \quad (2)$$

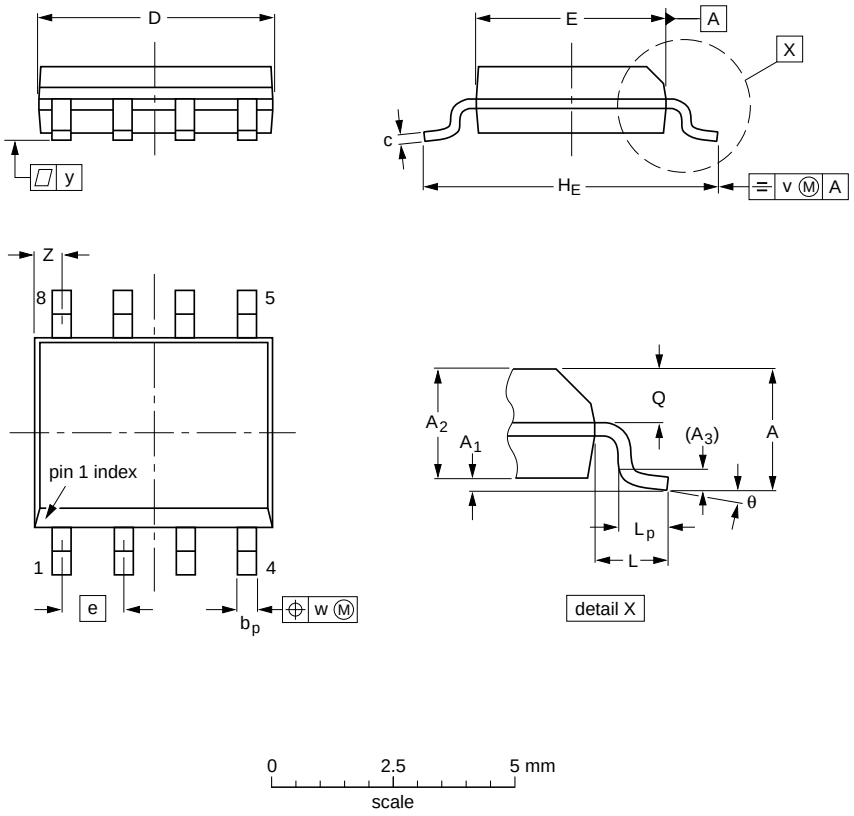
This can be compared with the offset characteristic shown in Figure 5.


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## 11. Package outline

**SO8: plastic small outline package; 8 leads; body width 3.9 mm** **SOT96-1**




**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

| UNIT | A max. | $A_1$ | $A_2$ | $A_3$ | $b_p$ | c | $D^{(1)}$ | $E^{(2)}$ | e | $H_E$ | L | $L_p$ | Q | v | w | y | $Z^{(1)}$ | θ |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| mm | 1.75 | 0.25<br>0.10 | 1.45<br>1.25 | 0.25 | 0.49<br>0.36 | 0.25<br>0.19 | 5.0<br>4.8 | 4.0<br>3.8 | 1.27 | 6.2<br>5.8 | 1.05 | 1.0<br>0.4 | 0.7<br>0.6 | 0.25 | 0.25 | 0.1 | 0.7<br>0.3 | $8^o$<br>$0^o$ |
| inches | 0.069 | 0.010<br>0.004 | 0.057<br>0.049 | 0.01 | 0.019<br>0.014 | 0.0100<br>0.0075 | 0.20<br>0.19 | 0.16<br>0.15 | 0.05 | 0.244<br>0.228 | 0.041 | 0.039<br>0.016 | 0.028<br>0.024 | 0.01 | 0.01 | 0.004 | 0.028<br>0.012 | |

**Notes**

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

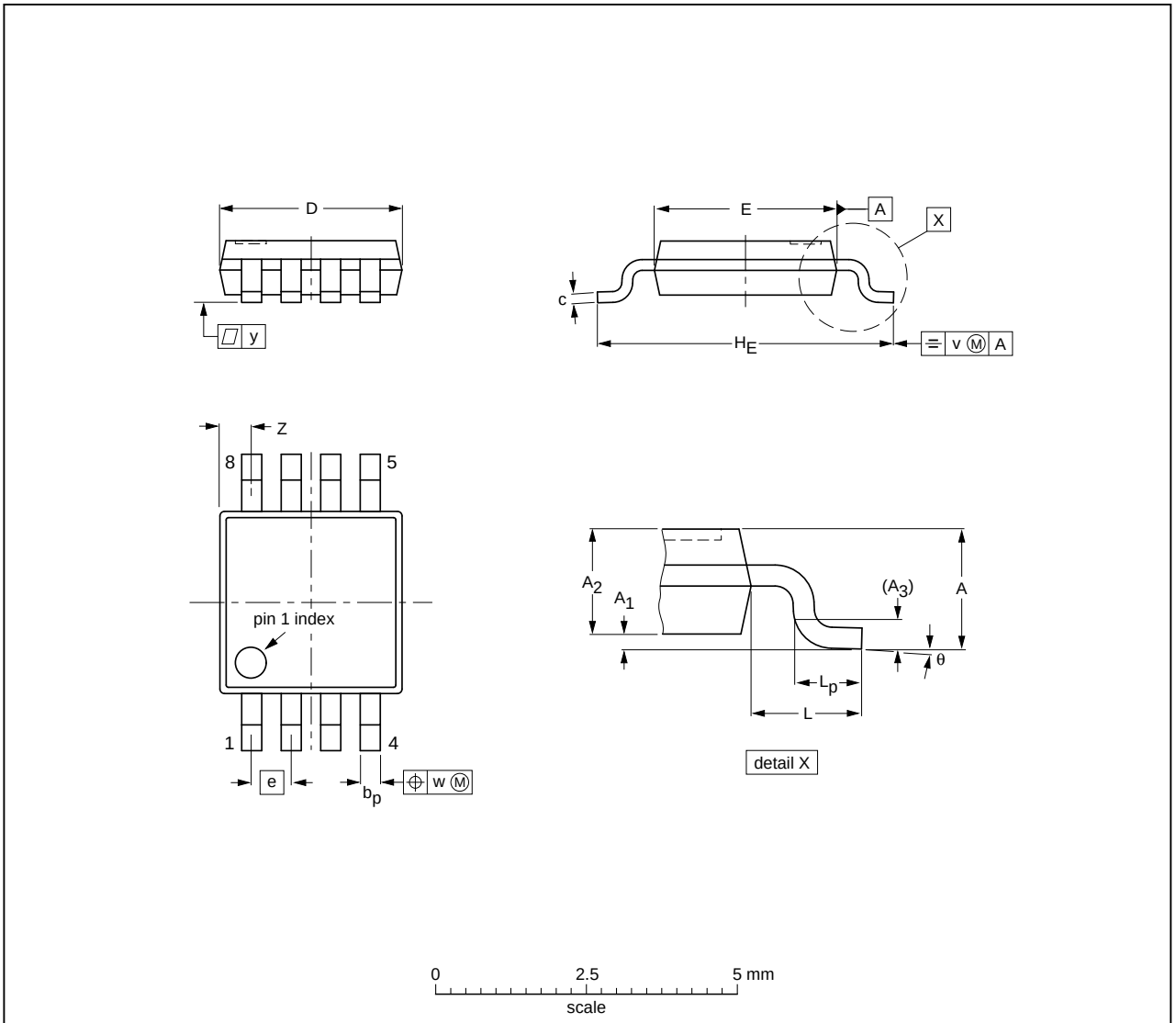
| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | JEITA | | | |
| SOT96-1 | 076E03 | MS-012 | | | | ~~99-12-27~~<br>03-02-18 |

**Fig 11. Package outline SOT96-1 (SO8)**


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**TSSOP8: plastic thin shrink small outline package; 8 leads; body width 3 mm** **SOT505-1**




**DIMENSIONS (mm are the original dimensions)**

| UNIT | A max. | $A_1$ | $A_2$ | $A_3$ | $b_p$ | c | $D^{(1)}$ | $E^{(2)}$ | e | $H_E$ | L | $L_p$ | v | w | y | $Z^{(1)}$ | θ |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| mm | 1.1 | 0.15<br>0.05 | 0.95<br>0.80 | 0.25 | 0.45<br>0.25 | 0.28<br>0.15 | 3.1<br>2.9 | 3.1<br>2.9 | 0.65 | 5.1<br>4.7 | 0.94 | 0.7<br>0.4 | 0.1 | 0.1 | 0.1 | 0.70<br>0.35 | 6°<br>0° |

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN PROJECTION | ISSUE DATE |
|---|---|---|---|---|---|---|
| | IEC | JEDEC | JEITA | | | |
| SOT505-1 | | | | | | ~~99-04-09~~<br>03-02-18 |

**Fig 12. Package outline SOT505-1 (TSSOP8)**


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# 12. Handling information

**CAUTION**



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices.

Such precautions are described in the *ANSI/ESD S20.20*, *IEC/ST 61340-5*, *JESD625-A* or equivalent standards.

# 13. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

## 13.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

## 13.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering


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## 13.3 Wave soldering

Key characteristics in wave soldering are:

- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

## 13.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 13) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 5 and 6

**Table 5. SnPb eutectic process (from J-STD-020C)**

| Package thickness (mm) | Package reflow temperature (°C) | |
|---|---|---|
| | Volume ($mm^3$) | |
| | < 350 | ≥ 350 |
| < 2.5 | 235 | 220 |
| ≥ 2.5 | 220 | 220 |

**Table 6. Lead-free process (from J-STD-020C)**

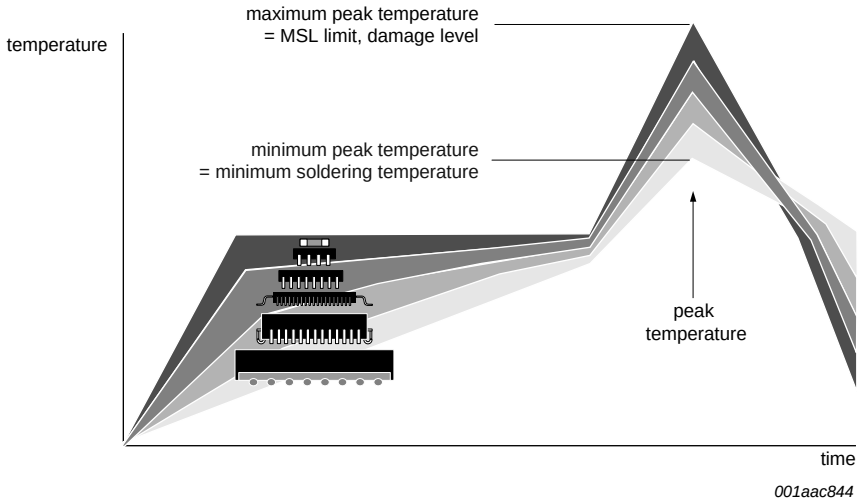
| Package thickness (mm) | Package reflow temperature (°C) | | |
|---|---|---|---|
| | Volume ($mm^3$) | | |
| | < 350 | 350 to 2000 | > 2000 |
| < 1.6 | 260 | 260 | 260 |
| 1.6 to 2.5 | 260 | 250 | 245 |
| > 2.5 | 250 | 245 | 245 |

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 13.


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MSL: Moisture Sensitivity Level

**Fig 13. Temperature profiles for large and small components**

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

## 14. Abbreviations

**Table 7. Abbreviations**

| Acronym | Description |
|---|---|
| AMC | Advanced Mezzanine Cards |
| ATCA | Advanced Telecommunications Computing Architecture |
| ESD | ElectroStatic Discharge |
| FRU | Field Replaceable Unit |
| $I^2C$-bus | Inter-Integrated Circuit bus |
| IC | Integrated Circuit |
| IPMB | Intelligent Platform Management Bus |
| PICMG | PCI Industrial Computer Manufacturers Group |
| PMBus | Power Management Bus |
| RAID | Redundant Array of Independent Discs |
| RTA | Rise Time Accelerator |
| ShMC | Shelf Management Controller |
| SMBus | System Management Bus |


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## 15. References

[1] **UM10204, I²C-bus specification and user manual —** , Rev 03, 19 June 2007; NXP B.V. www.nxp.com/documents/user_manual/UM10204.pdf

[2] **System Management Bus (SMBus) Specification —** Version 2.0, August 3, 2000; SBS Implementers Forum.

## 16. Revision history

**Table 8. Revision history**

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|---|---|---|---|---|
| PCA9522 v.1 | 20110928 | Product data sheet | - | - |


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|---|---|---|
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| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
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[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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**Date of release: 28 September 2011**
**Document identifier: PCA9522**